

ABSTRACT

The present disclosure provides a wafer and a method, an apparatus, a device and a medium for improving roughness thereof. The method includes: when a roughness is greater than or equal to a set roughness threshold, selecting a to-be-adjusted wire sawing parameter according to priorities of wire sawing parameters indicated by a fitting function between multiple wire sawing process parameters and the roughness in the target wavelength range, thereby reducing roughness in the target wavelength range of a bare wafer obtained from a subsequent wire sawing process.

(Figure 3)